

产 品 技 术 规 格 书

SPECIFICATION

产品型号 PART NO: LA31H2450-A35

客户料号 CUSTOMER PART NO:

客户确认 CUSTOMER APPROVED BY:

确认日期 APPROVED DATE:

RoHS Compliant Parts

中国浙江省嘉兴市经济开发区正原路 66 号

No.66 ZhengyuanRoad, Economic Development Zone,Jiaxing,Zhejiang,China

TEL: 0086-573-83651818

FAX: 0086-573-83651858

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嘉兴佳利电子有限公司 <http://www.glead.com.cn>
JIA XING GLEAD ELECTRONICS CO., LTD

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1. 概述 INTRODUCTION

"佳利"微波多层陶瓷天线 LA 系列产品设计用于 WLAN、WiFi、蓝牙、PHS，手机多频天线, FM 等小体积 SMD 片式设计。

"GLEAD" Microwave Multi-Layer Ceramic Antenna LA series are designed to be used in WLAN、WiFi、Bluetooth、PHS、 Multiple-band Mobile phone antenna, FM, etc and compact size SMD chip design.

2. 型号 Part Number

LA 31 H 2450 - A35

产品名称，编号 A35/Product Name: A35

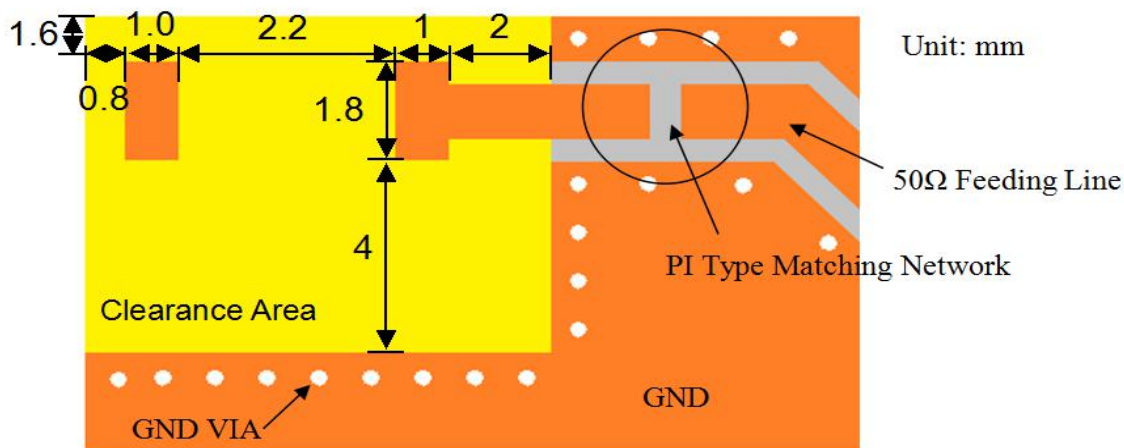
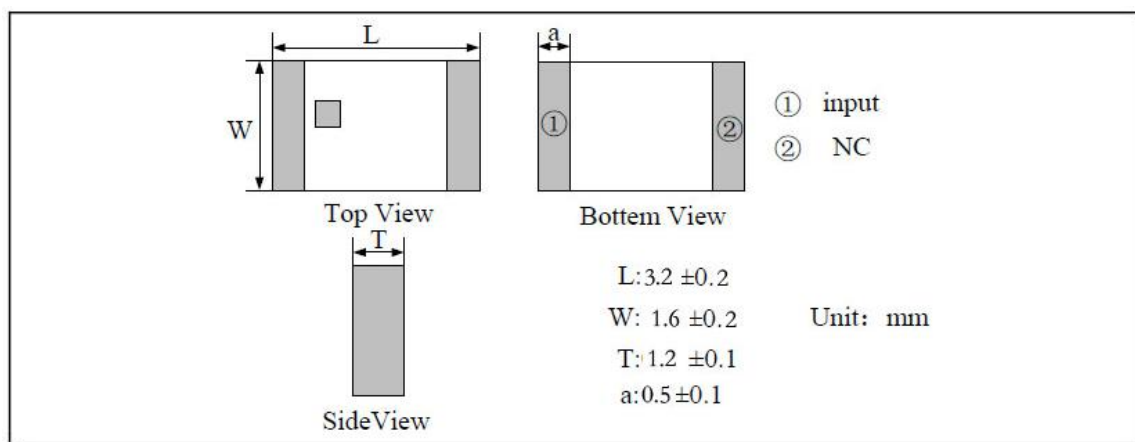
天线频率/ Antenna Frequency: 2450 MHz

产品设计结构 H 型/Via Design Series

产品尺寸/Size: $3.2 \times 1.6 \times 1.2$

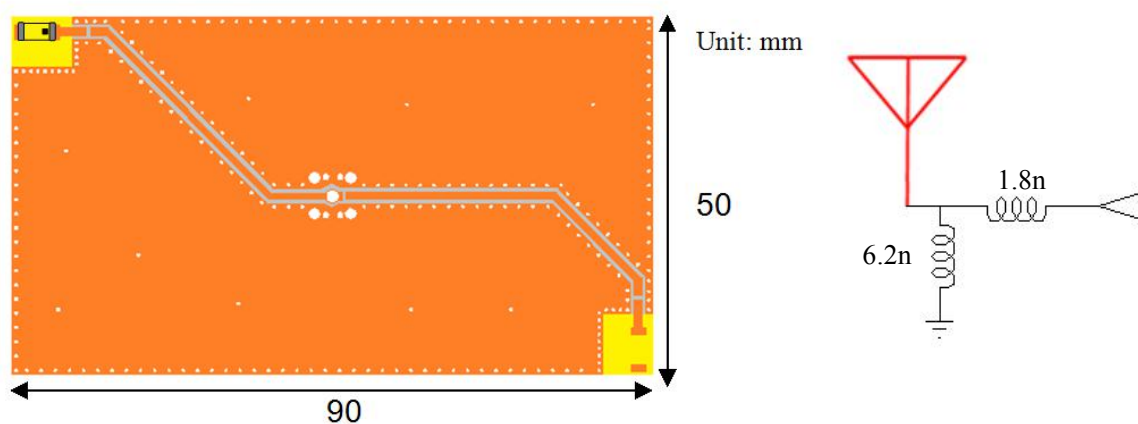
多层结构天线/Multi-layer Antenna

3. 外型尺寸 Dimensions (Unit: mm)



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4. 测试电路和匹配电路 Evaluation Board and Matching Circuits

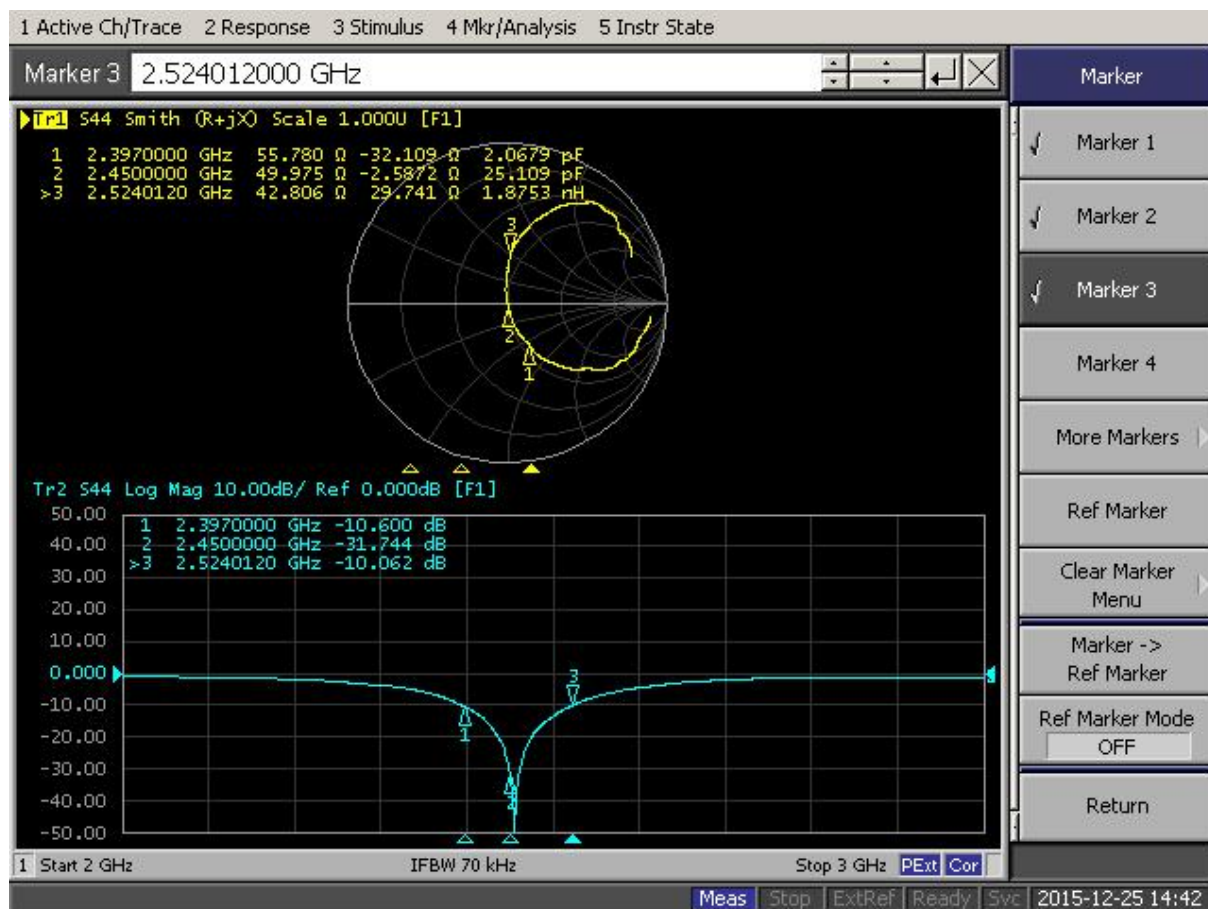


5. 电气性能 Electrical Characteristics

No.	Item (项目)	Specifications (特性)
5.1	Central Frequency 中心频率(No matching)	2412-2462MHz
	(带匹配电路测试)After Matching	2450 MHz
5.2	Band Width 通带宽度	100MHz typ.
5.3	Peak Gain 峰值增益	3.8dBi
5.4	V.S.W.R 驻波比	≤ 2.0
5.5	Polarization 极化方式	Linear 线性
5.6	Azimuth Beam width 方位角	Omni-directional 全向
5.7	Impedance 阻抗	50 Ω

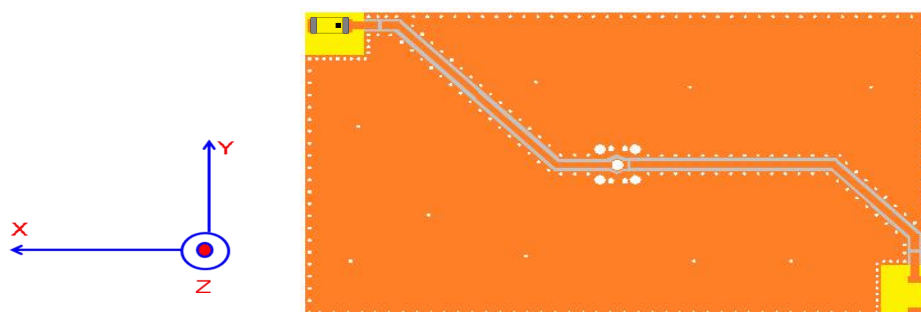
Specification

6. 特性曲线 Characteristic curve



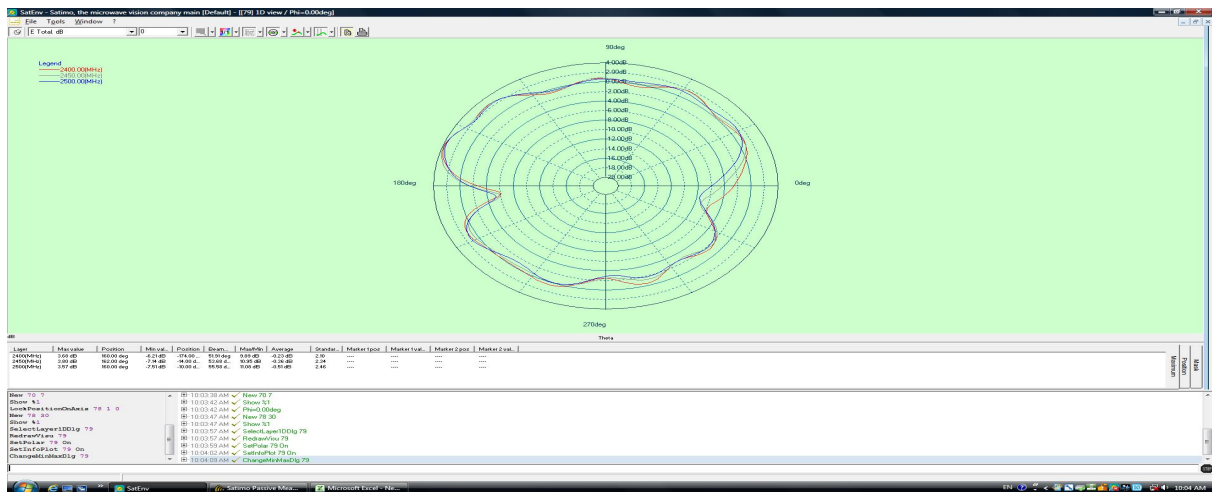
7. 方向图 Radiation Pattern

coordinates:

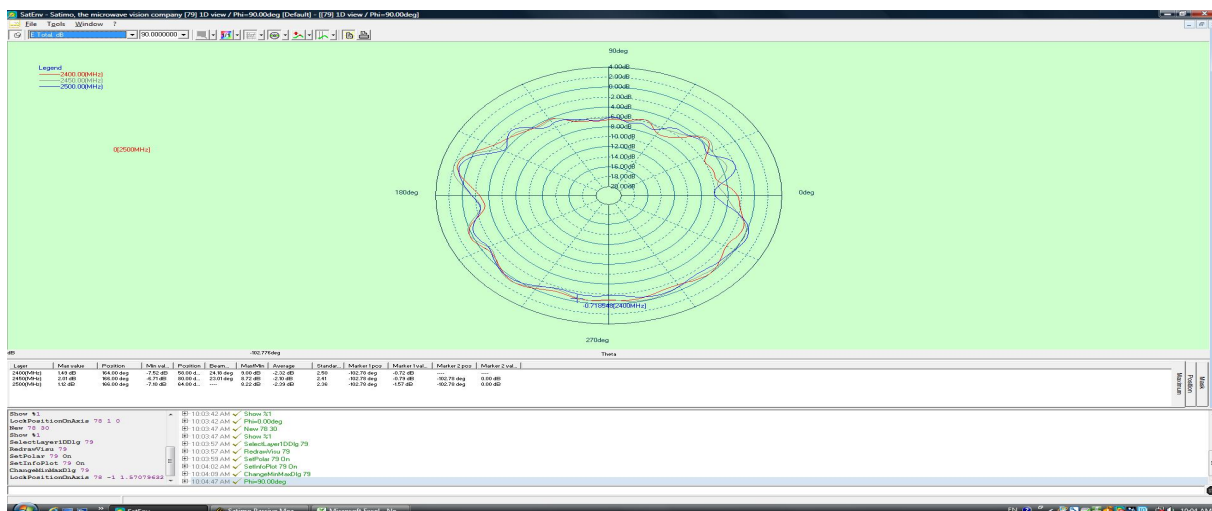


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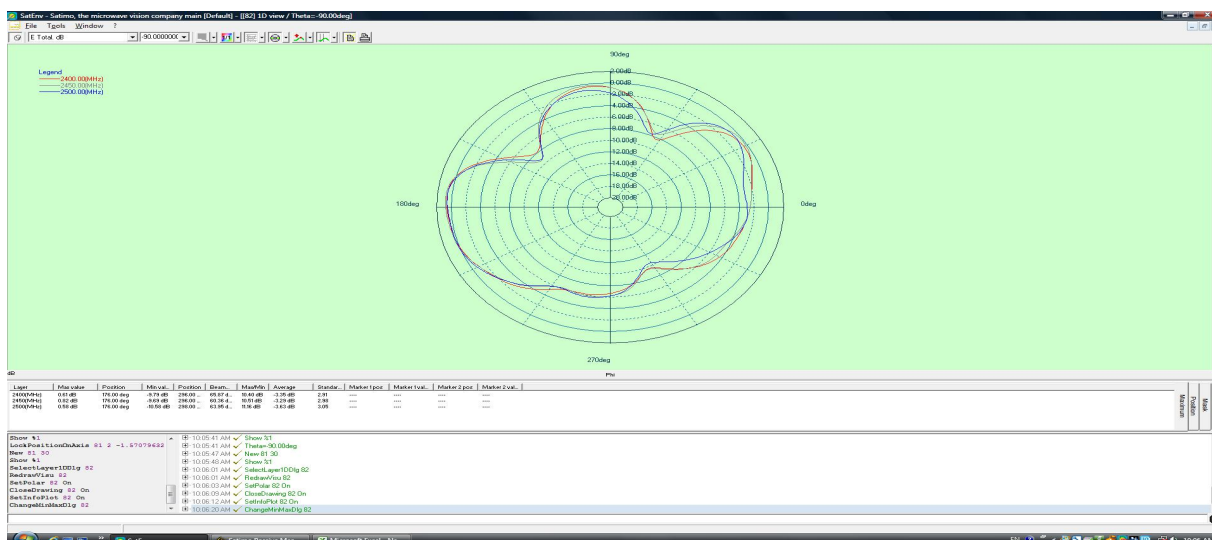
X-Z Plane



Y-Z Plane

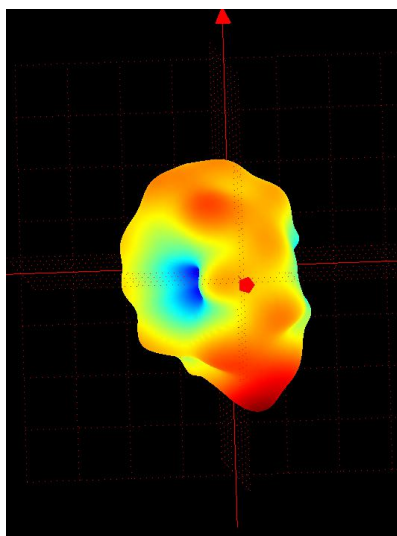


X-Y Plane



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3D Radiation Pattern



Frequency (MHz)	2400	2450	2500
Avg. Gain (dBi)	-0.23	-0.36	-0.51
Peck Gain (dBi)	3.68	3.8	3.57
Efficiency (%)	70	71.2	69

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8 可靠性试验后允许误差 Post Dependability Tolerance

经可靠性试验后允许比起始读数偏差见下表

Post Dependability Tolerance (Refer to the table)

No.	Item (项目)	Post Dependability Tolerance (可靠性试验后允许附加误差)
8.1	Central Frequency 中心频率	± 5 MHz
8.2	Band Width 通带宽度	± 5 MHz
8.3	Gain 增益	± 0.1 dBi
8.4	V.S.W.R (in BW) 驻波比	± 0.1

9 可靠性试验 Dependability Test

基准条件: 温度范围 Temperature range $25 \pm 5^{\circ}\text{C}$
 相对湿度范围 Relative Humidity range 55~75%RH
 工作温度 Operating Temperature range $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$

9.1 耐振动 Vibration Resist

在振动频率为 10~55Hz 振幅为 1.5mm 沿 X.Y.Z 方向各振动 2 小时后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

9.2 耐跌落冲击 Drop Shock

在 100cm 高度处按 X, Y, Z 三个面分别自由跌落在木制地板上共 3 次后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

9.3 耐焊接热 Solder Heat Proof

能承受经 $120 \sim 150^{\circ}\text{C}$ 的温度预热 120 秒后, 在 $255^{\circ}\text{C} + 10^{\circ}\text{C}$ 的焊锡浸 5 ± 0.5 秒, 或 $300^{\circ}\text{C} - 10^{\circ}\text{C}$ 的电烙铁焊接 3 ± 0.5 秒, 焊接面无损伤。

The device should be satisfied after preheating at $120^{\circ}\text{C} \sim 150^{\circ}\text{C}$ for 120 seconds and dipping in soldering Sn at $255^{\circ}\text{C} + 10^{\circ}\text{C}$ for 5 ± 0.5 seconds, or electric iron $300^{\circ}\text{C} - 10^{\circ}\text{C}$ for 3 ± 0.5 seconds, without damage.

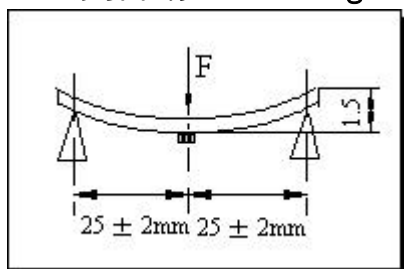
9.4 推力试验 Adhesive Strength of Termination

在产品电极端子上或表面上可承受 5N (≤ 0603); 10N (>0603) 水平推力 10 ± 1 秒而无明显外观损坏与电极移位。

The device have no remarkable damage or removal of the termination after horizontal force of 5N (≤ 0603); 10N (>0603) with 10 ± 1 seconds.

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9.5 耐弯曲试验 Bending Resist Test



将产品按图焊在 $1.6 \pm 0.2\text{mm}$ 的 PCB 板中间，由箭头方向施力： 1mm/S ，弯曲距离： 1.5mm ，保持 $5 \pm 1\text{S}$ ，产品金属层无脱落。

Weld the product to the center part of the PCB with the thickness $1.6 \pm 0.2\text{mm}$ as the illustration shows, and keep exerting force arrow-ward on it at speed of 1mm/S , and hold for $5 \pm 1\text{S}$ at the position of 1.5mm bending distance, so far, any peeling off of the

product metal coating should not be detected.

9.6 耐湿热特性 Moisture Proof

在温度为 $60 \pm 2^\circ\text{C}$ ，相对湿度 $90\sim 95\%$ 的恒温湿箱中放置 96 小时，在常温中恢复 $1\sim 2$ 小时后测试，符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature $60 \pm 2^\circ\text{C}$ and the relative humidity $90\sim 95\%$ RH for 96 hours and $1\sim 2$ hours recovery time under normal condition.

9.7 高温特性 High Temperature Endurance

在温度为 $125 \pm 5^\circ\text{C}$ 的恒温箱中放置 96 ± 2 小时，在常温中恢复 $1\sim 2$ 小时后测试。符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to temperature $125 \pm 5^\circ\text{C}$ for 96 ± 2 hours and $1\sim 2$ hours recovery time under normal temperature.

9.8 低温特性 Low Temperature Endurance

在温度为 $-40^\circ\text{C} \pm 5^\circ\text{C}$ 低温箱中放置 96 ± 2 小时后恢复 $1\sim 2$ 小时测试符合表 8.1~8.4 规定。

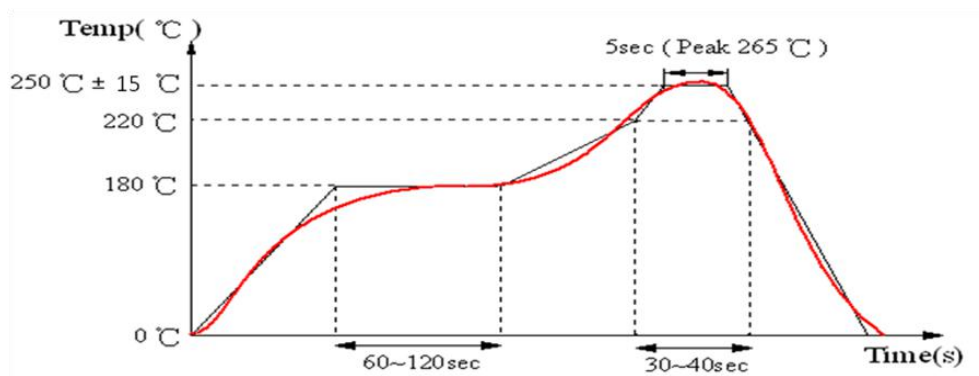
The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature $-40^\circ\text{C} \pm 5^\circ\text{C}$ for 96 ± 2 hours and to 2 hours recovery time under normal temperature.

9.9 温度循环 Temperature Cycle Test

在 -40°C 温度中保持 30 分钟，再在 $+125^\circ\text{C}$ 温度中保持 30 分钟，共循环 5 次后在常温中恢复 $1\sim 2$ 小时后测试符合表 8.1~8.4 规定。

The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the low temperature -40°C and high temperature $+125^\circ\text{C}$ for 30 ± 2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

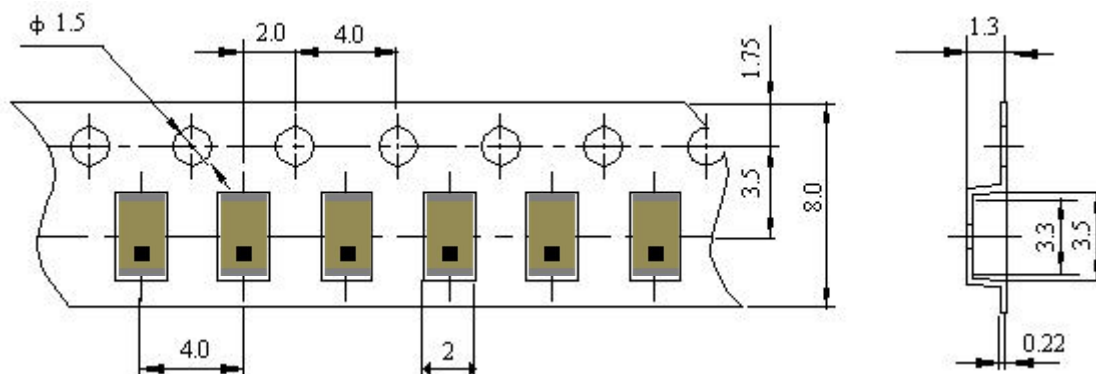
10 回流焊温度 Reflow Soldering Standard Condition



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11 包装尺寸 (3216) Packaging and Dimensions

11.1 Plastic Tape

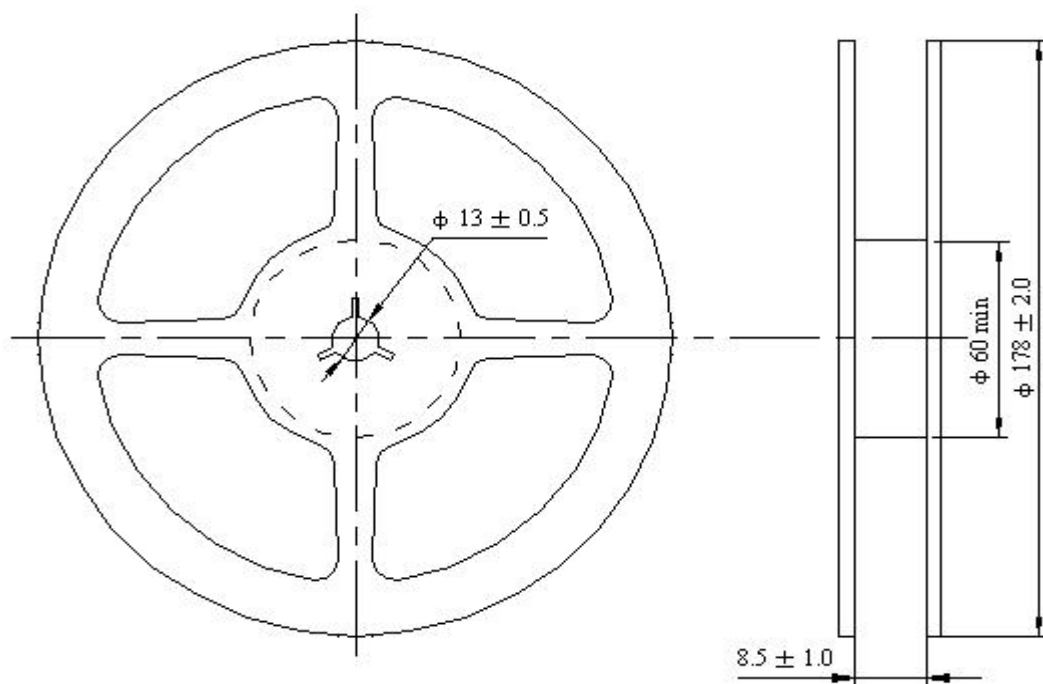


包装说明: Remarks for Package

载带尾部空穴长度 150~200mm, 载带头部空穴长度 250~300mm, 头部的盖带加长 250mm。

Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.

11.2 Reel (3000 pcs/Reel)



11.3 储存条件 Storage Period

产品收到后半年内使用完毕。

Product should be used within six months of receipt.

湿敏等级 1 / 储存温度与湿度:

MSL 1 / Storage Temperature Range : <30 degree C, Humidity : <85%RH